



I'm not robot



I am not robot!

Contact This standard prescribes the nomenclature, requirements and test methods for electronic grade solder alloys; for fluxed and non-fluxed bar, ribbon and powder solders for electronic soldering applications; and for "special" electronic grade solders IPC J-STDC CN 电焊领域电焊级焊料合金及含助焊剂与不含助焊剂的固体焊料的要求 由IPC组装与连接工艺委员会()焊料合金任务组(c)开发 由IPC TGAsia cCN 技术组翻译 鼓励本标准的使用者参加未来修订版的开发。联系方式: IPC Lakeside Drive Describes the nomenclature, requirements and test methods for electronic grade solder alloys; for fluxed and non-fluxed bar, ribbon, wire, and powder solders, for electronic soldering applications; and for 'special form' electronic grade solders This standard prescribes the nomenclature, requirements and test methods for electronic grade solder alloys; for fluxed and non-fluxed bar, ribbon, and powder solders, for electronic soldering applications; and for "special" electronic grade solders IPC J-STDC prescribes the nomenclature, requirements and test methods for electronic grade solder alloys; for fluxed and non-fluxed bar, ribbon and powder solders for electronic soldering applications; and for "special" electronic grade solders IPC/EIA-J-STDPDF Requirements for Electronic Grade Solder Alloys and Fluxed and Non-Fluxed Solid Solders for Electronic Soldering Applications IPC J-STDC. Developed by the Solder Alloy Task Group (c) of the Assembly and Joining Committee () of IPC. Users of this standard are encouraged to participate in the development of future revisions. Product Description. Final Draft for Industry Review Requirements for Electronic Grade Solder Alloys and Fluxed and Non-Fluxed Solid Solders for Electronic Soldering IPC J-STDC. for High Reliability Soldering. Requirements for Electronic Grade Solder Alloys and Fluxed and Non-Fluxed Solid Solders for Electronic Soldering Applications. Developed by the Solder Alloy Task Group (c) of the Assembly and Joining Committee () of IPC. Users of this standard are encouraged to participate in the development of future revisions. Contact For soldering applications that require maximum reliability of solder joints, especially for surface This standard prescribes the nomenclature, requirements and test methods for electronic grade solder alloys; for fluxed and non-fluxed bar, ribbon, and powder solders, for This standard prescribes the nomenclature, requirements and test methods for electronic grade solder alloys; for fluxed and non-fluxed bar, ribbon and powder solders for The J-STDC-AM1 amendment provides information on negative effects of adding rare earth elements to specific, heavy tin-containing, lead-free solder alloys and propensity of Requirements for Electronic Grade Solder Alloys and Fluxed and Non-Fluxed Solid Solders for Electronic Soldering Applications standard by Association Connecting Electronics IPC J-STDC. IPC/EIA-J-STDPDFREVISION C Leaded Solid Solder Wire. This standard prescribes the nomenclature, requirements and test methods for electronic grade solder alloys; for fluxed and non-fluxed bar, ribbon, wire, and powder solders, for Requirements for Electronic Grade Solder Alloys and Fluxed and Non-Fluxed Solid Solders for Electronic Soldering Applications. Requirements for Electronic Grade Solder Alloys and Fluxed and Non-Fluxed Solid Solders for Electronic Soldering Applications.